Test Data
For PMP10572
2/4/2015

TEXAS INSTRUMENTS
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1. Board Picture
Board Size: 56.8mm*14.4mm

2. Design Specifications

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<table>
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<tbody>
<tr>
<td>Vin Min.</td>
<td>40Vdc</td>
</tr>
<tr>
<td>Vin Max.</td>
<td>57Vdc</td>
</tr>
<tr>
<td>Vout</td>
<td>12Vdc</td>
</tr>
<tr>
<td>Iout</td>
<td>1A</td>
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3. TYPICAL PERFORMANCE

3.1 EFFICIENCY

![Efficiency Curve](image1)

3.2 Load regulation

![Load regulation Curve](image2)
3.3 Load Transient Response:
Ch3=Vo_ac(200mV/DIV), CH4=Io(0.5A/DIV)

Fig 3 Transient Response, Vin=40V DC Io=50%~100%~50%

Fig 4 Transient Response, Vin=48V DC Io=50%~100%~50%
3.4 Power up and Power down

Ch1=Vo(5V/DIV), Ch3=Vin(10V/DIV), CH4=Io(2A/div)
Fig 7 Vin=48V Io=1A Power up
**3.5 Ripple**

Ch1=Vo_ac (200mV/DIV) with 20 MHz Bandwidth (have a 0.1uF ceramic cap at output port)
Fig 10 VIN=40V, Io=1A,

Fig 11 VIN=48V, Io=1A,
3.6 SW and Diode Stress

Fig 12 VIN=57VDC, Io=1A,

Fig 13 VIN=40VDC, Io=1A
3.7 Short
Ch2=Vo(5V/DIV), Ch4=Io(2A/DIV)
3.8 Thermal-test in the room temp:

Figure 17 Vin=48V Io=1A
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